## 1000MHz, 80W, 50V High Power RF LDMOS FETs

### **Description**

The M2U1008V is a 80-watt, highly rugged, unmatched LDMOS FET, designed for wideband commercial and industrial applications at frequencies HF to 1.0 GHz. It can support pulsed, CW or any modulated signal in form of linear or saturated

It can support pulsed, CW or any modulated signal in form of linear or saturated operations.



•Typical Performance (On Innogration narrow band fixture with device soldered): Pulsed CW, 20uS width, 10% dule cycle

Vds= 50V,IDQ =80mA(Vgs =3.22V)							
Freq (MHz) P1dB(dBm) P1dB(W) P1dB Eff(%) P1dB Gain(dB) P3dB(dBm) P3dB(W) P3dB Eff(%)							
915	49.12	81.59	63.91	22.98	49.78	95.07	63

#### **Features**

- · High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

### **Suitable Applications**

- 2-30MHz (HF or Short wave communication)
- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 118 -140MHz (Avionics)

- 136-174MHz (Commercial ground communication)
- 160-230MHz (TV VHF III)
- 30-512MHz (Jammer, Ground/Air communication)
- 470-860MHz (TV UHF)
- 100kHz 1000MHz (ISM, instrumentation)

#### **Table 1. Maximum Ratings**

•			
Rating	Symbol	Value	Unit
DrainSource Voltage	V <sub>DSS</sub>	110	Vdc
GateSource Voltage	V <sub>GS</sub>	-10 to +10	Vdc
Operating Voltage	V <sub>DD</sub>	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

#### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Rejc	1.5	°C/W
T <sub>C</sub> = 85°C, T <sub>J</sub> =200°C, DC test	Keac	1.5	-0/00

### **Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2

60

-5

%

dΒ

# **M2U1008V LDMOS TRANSISTOP**

Table 4. Electrical Characteristics (TA = 25  $^{\circ}$ C unless otherwise noted)

Drain Efficiency@Pout

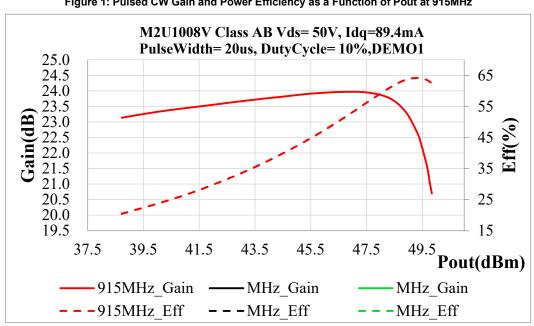
Input Return Loss

Characteristic	Symbol	Min	Тур	Max	Unit
DC Characteristics					
Drain-Source Voltage	V		110		V
V <sub>GS</sub> =0, I <sub>DS</sub> =1.0mA	$V_{(BR)DSS}$				
Zero Gate Voltage Drain Leakage Current				1	^
$(V_{DS} = 50V, V_{GS} = 0 V)$	I <sub>DSS</sub>			1	μΑ
GateSource Leakage Current				4	^
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$	I <sub>GSS</sub>			1	μΑ
Gate Threshold Voltage	M. m.		0.70		
$(V_{DS} = 50V, I_D = 600 \mu A)$	V <sub>GS</sub> (th)		2.73		V
Gate Quiescent Voltage	V		3.22		
$(V_{DD}$ = 50 V, $I_{D}$ = 80 mA, Measured in Functional Test)	$V_{GS(Q)}$		3.22		V
Common Source Input Capacitance	C <sub>ISS</sub>		57		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$					
Common Source Output Capacitance	Coss		24		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$					
Common Source Feedback Capacitance	C <sub>RSS</sub>		0.75		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$					
Functional Tests (In Demo Test Fixture, 50 ohm system) V <sub>DD</sub> = 50 Vd	c, I <sub>DQ</sub> = 80mA, f =	915 MHz, CW	/ Signal Measu	rements, Pin=	27dBm
Power Gain@Pout	Gp		22		dB
Output Power	Pout		80		W

### TYPICAL CHARACTERISTICS

 $\eta_{\mathsf{D}}$ IRL

Figure 1: Pulsed CW Gain and Power Efficiency as a Function of Pout at 915MHz

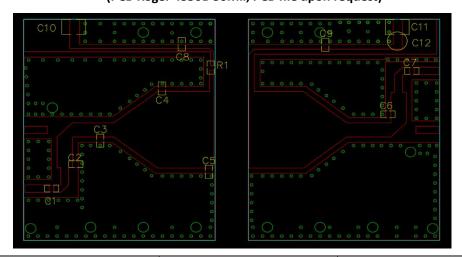


# **M2U1008V LDMOS TRANSISTOP**

>1 915.00000 MHz -5.5510 dB 20.00 15.00 10.00 5.000 0.000 -10.00 -15.00 -20.00 -25.00 [FZ] S21 Log Mag 20.00 db/ Ref -20.00 db [ER D&M] >1 915.00000 MHz 19.027 dB 60.00 40.00 20.00 -20.00 -40.00 -60.00 -80.00 -100.0 -120.0

Figure 2: Network analyzer output S11/S21

Figure 3. Test Circuit Component Layout (PCB Roger 4350B 30Mil, PCB file upon request)



Component	Value	Quantity
U1	M2U1008V	1
C1、C7、C8、C9	33pF	4
C3、C4、C5	15pF	3
C2	1.5pF	1
C6	10pF	1
C12	470uF/63V	1
C10、C11	10uF	2
R1	10 Ω	1

# **M2U1008V LDMOS TRANSISTOP**

# **Package Outline**

Flanged ceramic package; 2 leads

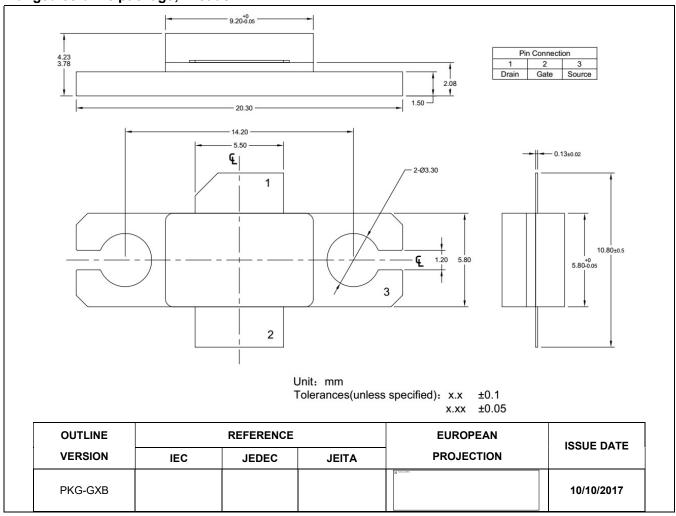


Figure 1. Package Outline PKG-G2E

# **M2U1008V LDMOS TRANSISTOP**

Document Number: M2U1008V Preliminary Datasheet V1.0

## **Revision history**

**Table 5. Document revision history** 

Date	Revision	Datasheet Status
2022/12/5	V1.0	Preliminary Datasheet Creation

Application data based on ZYX-22

#### **Disclaimers**

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